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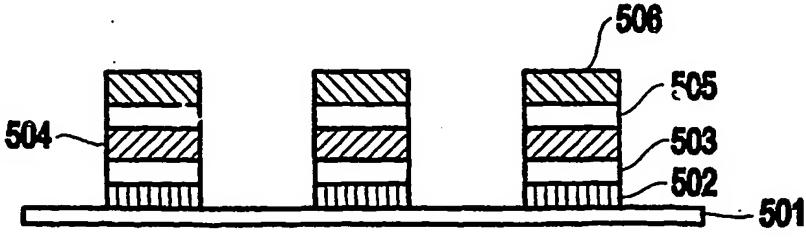
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(54) Title: METHOD OF SELF-ASSEMBLING ELECTRONIC CIRCUITRY AND CIRCUITS FORMED THEREBY



(57) Abstract: A method of assembling a circuit includes providing a template, enabling a semiconductor material to self assemble on the template, and enabling self-assembly of a connection between the semiconductor material and the template to form the circuit and a circuit created by self-assembly.

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